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# Single-longitudinal-mode InGaAsSb/AlGaAsSb lasers for gas sensing

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**Abstract.** Regrowth-free gain-coupled GaSb-based DFB lasers suitable for gas sensing were fabricated. Threshold currents for 2.4μm emission of 400μm-long DFB devices were 45mA with a total output power of nearly 11mW in CW operation at 20°C.

**Resumen.** Se reporta sobre la fabricación de lásers de semiconductor de retroalimentación distribuida (Distributed feedback lasers o DFB) para el monitoreo de gases. El material de los lásers fue desarrollado sobre cristales de GaSb. Se empleo un método novedoso de fabricación para lograr el acomplamiento por ganancia, lo cual elimina la necesidad de re-crecimiento epitaxial. Lásers de 400μm de longitud, que emiten a una longitud de onda de 2.4μm, presentaron una corriente de umbral de 45mA y una potencia de salida de 11mW en operación en corriente continua (CC) a una temperatura de 20°C.

Palabras clave. Semiconductor lasers, 42.55.Px, Gas sensors, 07.07.Df.

### 1 Introduction

Ever-increasing global concerns over such issues as pollution, health, workplace safety, and industrial process control are requiring intensified research on gas sensors. Fortunately, semiconductor lasers emitting in the 2-5 $\mu$ m spectral region, where many gaseous byproducts of industrial processes have strong absorption features, can be used to monitor gas emissions using tunable diode laser absorption spectroscopy (TDLAS)<sup>1</sup>.

In the case of GaSb-based laser diodes, the development of these systems has been hindered by the complexities of epitaxial regrowth and the use of aluminum containing compounds in the cladding layers. We have circumvented this problem by employing a material-independent, regrowth-free process that could be used to fabricate gain-coupled single frequency lasers regardless

of the substrate and epilayer materials<sup>2</sup>. This process also has the advantage that facet coatings are not needed for single mode operation.

In this work, we describe device processing and optical characterization of Sb-based tunable distributed feedback lasers (DFBs) with emission near  $2.4\mu m$ .

#### 2 Growth

The laser structures were grown on GaSb substrates by molecular beam epitaxy in a custom V90 system using conventional group-III effusion cells and valved cracker cells for  $As_2$  and  $Sb_2$ . The laser structure consists of  $2\mu$ m-thick Te- and Be-doped  $Al_{0.6}Ga_{0.4}As_{0.0516}Sb_{0.9484}$  cladding layers lattice-matched to the GaSb substrate. Uniform doping of  $2x10^{18}$  cm<sup>-3</sup> was used throughout the n-cladding, while the p-cladding doping was carefully

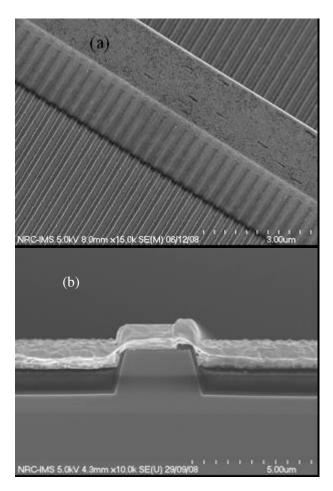
graded close to the waveguide to reduce optical losses. The active region contains three  $94.2\mathring{A}$  The active region contains three  $In_{0.4}Ga_{0.6}As_{0.14}Sb_{0.86}$  quantum wells separated by  $300\mathring{A}$   $Al_{0.24}Ga_{0.76}As_{0.021}Sb_{0.979}$  barriers, embedded in an  $Al_{0.24}Ga_{0.76}As_{0.021}Sb_{0.979}$  waveguide with a total thickness of  $0.53\mu m$ . This structure was designed using the approach of Ref. [3] which uses a broader optical waveguide mode in order to reduce the fast-axis beam divergence.

# 3 Fabrication

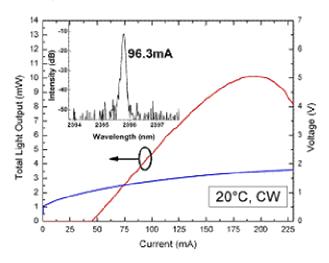
Fabrication of single-mode distributed feedback lasers (DFBs) followed, in essence, the method outlined in Ref. [2] which involves the deposition of lateral metal gratings on either side of a narrow ridge waveguide to provide evanescent coupling to the optical mode. Twinchannel ridges were fabricated using inductively-coupled plasma reactive ion etching (ICP-RIE) with BCl<sub>3</sub>/Ar chemistry. The etch process was tailored to produce waveguides with both, smooth sidewalls to reduce optiscattering losses, and slanted sidewalls, 12° from the vertical to allow for uniform resist coating across waveguides. A JEOL 6000 e-beam lithography tool with fine-pitch control was used to write a grating lift-off pattern across the ridges using ZEP resist. Firstorder Cr gratings with a 50% duty cycle and a thickness of 40nm were deposited using e-beam evaporation. A first sacrificial planarization step was used in conjunction with a Cl<sub>2</sub>-O<sub>2</sub> etch in an ICP-RIE for removal of the Cr around the top of the ridge. This step is necessary to electrically isolate the top p-contact from the Cr grating, see Fig. 1(a). A 150nm SiO<sub>2</sub>-PECVD layer was then deposited across the entire sample. The oxide on top of the ridges was removed by patterning windows on the ridges and etching the oxide in an RIE with CHF3-O2 chemis-

Channel planarization was carried out with Polyimide, PI2562, which was baked at 240°C under controlled temperature ramping, and cooled down to room temperature. A second layer of Polyimide was spun on the samples to improve planarization following the same temperature treatment. Polyimide was finally cured at 400°C for 6 min in  $N_2$  atmosphere. Surface morphology was further smoothened by spinning Futurrex planarizing coating PC3-1500 on the samples. Top of the ridges were cleared of planarizing coating and polyimide with a dryetch in  $O_2$  atmosphere.

Prior to top contact metallization, native oxide removal was accomplished by immersing the samples in 10 H<sub>2</sub>O: 1 HCl for 30sec, followed by a 30sec rinse in de-ionized water. A TiPtAu p-contact stack was deposited immediately on top of the ridges. After wafer thinning, and sample encapsulation with PMMA, NiGeAu was deposited by e-beam evaporation on the backside of the samples for n-contact metallization. Samples were subsequently cleaved in bars or individual chips for electrical and optical characterization. See Fig. 1(b).



**Figure 1.** (a) Slanted SEM view of ridge waveguide after Cr deposition and lift-off which also shows the Cr etch around top of waveguide, (b) SEM cross-section of finished DFB laser.



**Figure 2.** Output power characteristics of  $4\mu m \times 400\mu m$  DFB laser operating CW at a temperature of  $20^{\circ}$ C. Facets were not coated. Gain coupling was obtained with a 1st-order Cr grating with 50% duty cycle. Inset shows single mode emission at 2395.8 nm.

The effect of lhigh reflection (HR) and anti-reflection (AR) coatings was also investigated and compared to ascleaved (CL) facets. The HR mirror stack was set at 99% reflectivity and the AR at 0.1%.

# 4 Characterization

The threshold current for a 400µm-long DFB device was 45mA with a total output power of nearly 11mW in CW operation at 20°C. See Fig. 2. The emission spectra are single-mode throughout the entire range of operation, indicating a strong grating coupling, even for a rather short cavity length.

The effect of facet coatings was evident on the power output and the slope efficiency. Power output increased by 25% with an HR-CL combination, and by 50% with an HR-AR combination. Similarly, slope efficiency increased from 27mW/A for a CL-CL laser bar, to 35mW/A for an HR-CL, to 53mW/A for an HR-AR combination.

The current tuning was well-described by a second-order polynomial, and at the target wavelength of 2395.8nm the tuning was 0.062nm/mA. See Fig. 3. Adjustment of the heatsink temperature results in a tuning coefficient of 0.2nm/K. The DFB wavelength can also be readily adjusted by varying the grating pitch,  $\Lambda$ , e.g. the wavelength was shifted from 2396nm to 2376nm by varying  $\Lambda$  from 339.6nm to 336.65nm. This provides a means of monitoring many gases using lasers from a single epi-wafer by adjusting the grating pitch, operating temperature and current of individual emitters.

#### **Conclusions**

We have fabricated regrowth-free tunable DFB lasers emitting at  $2.4\mu m$  on GaSb-based material. Threshold currents of  $400\mu m$ -long DFB devices were around 45mA with a total output power of nearly 11mW in CW operation at  $20^{\circ}C$ . We can envision using these lasers in portable gas detectors, as well as, in line-of-sight gas sensing applications.

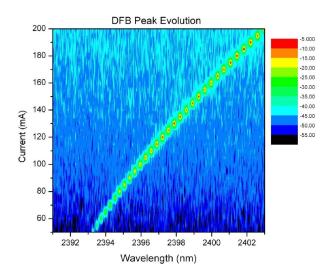


Figure 3. Single-mode tuning with applied injection current

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